

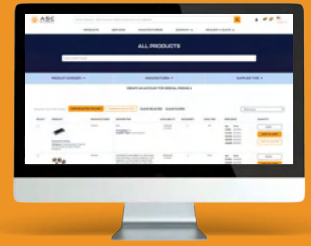
MARKET REPORT Q3 2026

DIODES INC. SHORTAGE & INDUSTRIAL MICROSD SOLUTIONS



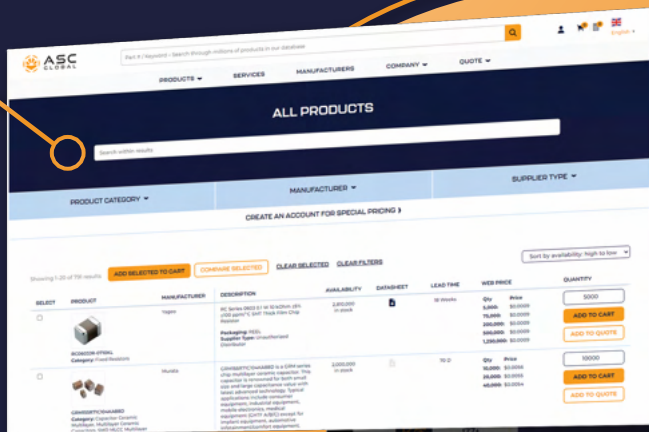
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ASC Global delivers cutting-edge industry insights and trends. The following sections provide valuable information gathered from research, expert insights from our team, and reliable sources in the industry.

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Lead-Time Report

The following insights stem from thorough research of ASC Global's marketing team combined with the expertise of all our departments. The information is designed to provide guidance and should be approached as such.

ASC Global excels in supply chain strategies that effectively address market volatility. For a deeper understanding, kindly reach out to your Account Manager.



Stable



Increasing



Decreasing



End-of-life

Analog

Power

Passives

Memory

Logic & Digital

Electromechanical

< Analog >

Factory Lines

Product	Brand	Lead time weeks	Prognosis	Pricing Trend
Gate Drivers	Power Integrations	14-18	↑	↔
	ROHM	16-20	↑	↔
	Silergy	16-20	↑	↔
	Allegro MicroSystems	20-22	↔	↑
LED Drivers	Diodes Incorporated	16-24	↑	↑
	MPS	24-36	↑	↑
	ROHM	16-26	↑	↔
	STMicroelectronics	18-24	↑	↑
Timing	Onsemi	22-32	↔	↑
	Microchip	7-12	↔	↔
	Renesas	20-26	↑	↑

Open Market

Availability	Pricing Trend
↔	↔
↔	↔
↔	↔
↔	↔
↔	↑
↔	↔
↔	↔
↔	↑
↔	↑
↔	↔
↑	↑

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Interface	NXP	10-20	↔	↑	↔	↑
	Renesas	12-14	↑	↑	↔	↑
Amplifiers and Data Converters	Microchip	4-10	↔	↔	↔	↔
	Onsemi	10-16	↔	↑	↔	↔
	Renesas	14-16	↑	↑	↔	↑
	STMicroelectronics	20-22	↑	↑	↔	↑
Power Converters/ Controllers	Infineon	8-12	↔	↔	↔	↔
	MPS	24-44	↑	↑	↔	↑
PMIC	Nordic Semiconductor	18-20	↔	↔	↔	↔
	NPX	22-24	↔	↑	↔	↑

AI infrastructure and industrial electronics continued driving activity across analog semiconductors. Texas Instruments expanded pricing for power management ICs, digital isolators, and isolated gate drivers, while Analog Devices, STMicroelectronics, Infineon Technologies, and NXP Semiconductors maintained focus on automotive, energy, and industrial analog portfolios.

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- Excess Stock Management
- EOL & Obsolescence Management
- Exclusive Pricing & Rebates
- Yearly Contracts



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Power

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
IGBT's	STMicroelectronics	14-24	↑	↔	↔	↔
	Littelfuse	15-60	↔	↑	↔	↑
	Microchip	12-26	↔	↔	↔	↔
	Infineon	12-52	↑	↑	↔	↑
High Voltage MOSFET's	Infineon	12-52	↑	↑	↔	↑
	Littelfuse	23-52	↔	↑	↔	↑
	Microchip	6-28	↑	↑	↔	↑
	STMicroelectronics	12-26	↑	↑	↔	↑
Low Voltage MOSFET's	Infineon	12-52	↑	↑	↔	↑
	ONSEMI	10-52	↑	↑	↔	↑
	Vishay	12-52	↑	↑	↔	↑
	STMicroelectronics	10-23	↑	↑	↔	↑
Wide Bandgap MOSFET's	Littlefuse	27-29	↔	↔	↔	↔
	Infineon	12-52	↑	↑	↔	↑
	ONSEMI	14-52	↑	↑	↔	↑
	STMicroelectronics	20-32	↑	↔	↔	↑
Rectifiers	Diodes Incorporated	24-30	↑	↑	↔	↑
	ONSEMI	20-24	↔	↔	↔	↔
	STMicroelectronics	14-16	↔	↔	↔	↔
	Vishay	8-10	↔	↑	↔	↑

Power semiconductor suppliers continued expanding high-efficiency portfolios for automotive, industrial, and energy systems. Infineon Technologies, STMicroelectronics, Toshiba, and Nexperia emphasized IGBTs, super-junction MOSFETs, SiC MOSFETs, and rectifiers, prioritizing higher power density, improved thermal performance, and greater efficiency for EV, renewable energy, and industrial power conversion applications.

Passives

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Capacitors	Kyocera	14-16	↔	↔	↔	↑
	Abracon	20-22	↔	↔	↔	↔
	EATON	10-20	↔	↑	↔	↑
	Vishay	12-14	↔	↑	↔	↑
Resistors	ROHM	8-10	↔	↔	↔	↑
	Samsung	44-46	↔	↔	↔	↑
	Panasonic	12-16	↑	↑	↔	↑
	Vishay	10-14	↔	↔	↔	↑
Inductors/Transformers	EATON	12-16	↔	↑	↔	↑
	Vishay	10-12	↔	↑	↔	↑
	Panasonic	23-25	↔	↔	↔	↔
	Murata	8-12	↔	↑	↔	↑
Surface Mount General Capacitors	TDK	20-24	↑	↑	↔	↑
	Samsung	20-24	↑	↔	↔	↔
	Kyocera	24-30	↑	↑	↔	↑
	Vishay	16-18	↑	↑	↔	↑
Aluminum Electrolytic	AiSHi	16-20	↑	↑	↔	↑
	Nichicon	26-36	↑	↑	↔	↑
	Panasonic	18-40	↑	↑	↔	↑
Filters	TDK	14-20	↑	↑	↔	↑
	Murata	24-30	↑	↑	↔	↑
	TAIYO YUDEN	20-26	↑	↑	↔	↑

Manufacturers continued advancing passive component portfolios for high-reliability applications. Exxelia introduced CF-PP140 film capacitors for high-temperature power systems, Bourns released MH3261 ferrite beads, and Stackpole Electronics expanded high-voltage chip resistors, while automotive and AI infrastructure sustained demand for advanced inductors and precision passives.

Memory

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
NAND Flash	Alliance Memory	16-24	↑	↑	↓	↑
	GigaDevice	12-26	↑	↑	↓	↑
	Macronix	30-52	↑	↑	↓	↑
NOR Flash	Alliance Memory	12-20	↑	↑	↓	↑
	GigaDevice	12-26	↑	↑	↓	↑
	Infineon	20-26	↑	↑	↓	↑
Memory Modules	Centon	26-52	↑	↑	↓	↑
	Kingston	6-12	↑	↑	↓	↑
	ADATA	26-52	↑	↑	↓	↑
	SMART Modular	26-52	↑	↑	↓	↑
SRAM	Renesas	20-24	↔	↔	↓	↔
	ONSEMI	20-40	↔	↔	↓	↑
	Microchip	4-11	↔	↔	↓	↑
	Alliance Memory	8-30	↑	↔	↓	↔
EEPROM	STMicro	12-20	↑	↑	↓	↑
	ONSEMI	12-20	↔	↔	↓	↔
	ROHM	4-25	↔	↔	↔	↔
	Microchip	4-25	↔	↔	↔	↔
NOR Flash	Microchip	4-26	↔	↔	↔	↔
	Renesas	12-16	↑	↑	↔	↑
	Infineon	20-26	↑	↑	↔	↑
	Alliance Memory	12-20	↑	↑	↓	↑


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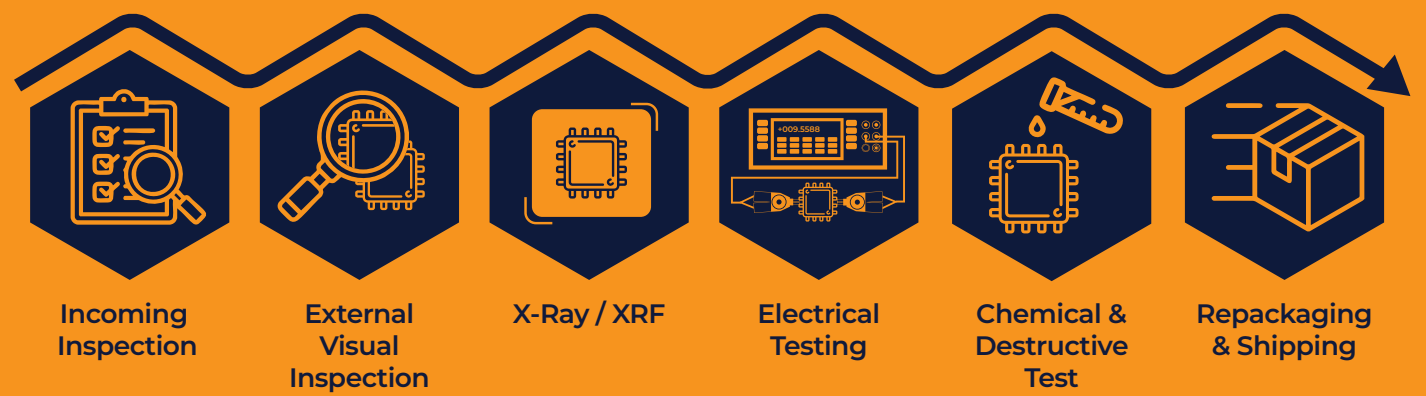
Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
eMMC	ADATA	26-52	↑	↑	↓	↑
	Greenliant	26-52	↑	↑	↓	↑
	Alliance Memory	26-52	↑	↑	↓	↑
	Kingston	24-26	↑	↑	↓	↑
PC (Commodity) DRAM	Kingston	24-26	↑	↑	↓	↑
	Alliance Memory	8-52	↑	↑	↓	↑
Solid State Drives	Kingston	24-26	↑	↑	↓	↑
	Greenliant	26-52	↑	↑	↓	↑
	ADATA	26-52	↑	↑	↓	↑

Memory suppliers continued prioritizing AI-focused products throughout Q2 2026. Micron Technology, Samsung Electronics, and SK hynix expanded HBM4, DDR5, and NAND production, while all three secured certification for NVIDIA's Vera Rubin platform, reinforcing AI memory roadmaps and enterprise server deployments.



Counterfit Detection

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Logic & Digital

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
8 Bit MCU	Renesas	14-18	↑	↔	↔	↔
	Microchip	4-12	↔	↔	↔	↔
	STMicro	20-30	↑	↑	↔	↑
	NXP	16-39	↔	↔	↔	↔
32 Bit MCU	Infineon	10-97	↑	↔	↔	↔
	Microchip	4-18	↑	↔	↔	↔
	STMicro	16-20	↑	↔	↔	↔
	NXP	16-39	↔	↔	↔	↔
FPGA	Microsemi	12-30	↑	↔	↔	↔
	Efinix	19-36	↑	↑	↔	↑
USB	Infineon	12-16	↔	↑	↔	↑
	Microchip	6-16	↑	↔	↔	↑
Automotive	STMicro	40-52	↔	↔	↔	↔
	NXP	18-52	↔	↔	↔	↔
	Renesas	12-24	↔	↔	↔	↔
LCD's	Sharp	14-28	↔	↔	↔	↔
	WiseChip	14-16	↔	↔	↔	↔
	AZ Displays	14-16	↑	↑	↔	↑
SOM	iWaveSystems	14-26	↔	↔	↔	↔
	TechNexion	13-26	↑	↑	↔	↑

Manufacturers continued advancing embedded computing platforms in Q2 2026. Lattice Semiconductor expanded CrossLinkU-NX FPGA SoMs for edge AI and vision systems, while Renesas Electronics, NXP Semiconductors, and Microchip Technology strengthened 8-bit/32-bit MCU portfolios. Industrial LCDs and SoMs remained focused on long-lifecycle embedded applications.

Electromechanical

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Relays	TE Connectivity	18-20	↑	↑	↔	↑
	Panasonic	14-30	↑	↑	↔	↑
	Infineon	40-52	↔	↑	↔	↑
	American Zettler	16-30	↔	↑	↔	↑
Switches	Panasonic	10-12	↔	↔	↔	↔
	TE Connectivity	10-12	↔	↑	↔	↑
	ZF Electronics	18-20	↔	↑	↔	↑
	Grayhill	12-24	↔	↑	↔	↑
Timing	Microchip	12-52	↑	↑	↔	↑
	Kyocera	12-28	↔	↑	↔	↑
	Epson	12-24	↑	↑	↔	↑
	Abrakon	12-30	↑	↑	↔	↑
Fans	SUNON	24-26	↔	↔	↔	↔
	Qualtek	20-24	↔	↑	↔	↑
	BOYD	12-14	↔	↔	↔	↔
	ADDA	20-24	↔	↔	↔	↔
Power Supplies (AC/DC)	CUI Inc.	14-28	↔	↑	↔	↑
	MEAN WELL	14-17	↔	↔	↔	↔
	Murata PS	14-38	↔	↑	↔	↑
	Recom	16-36	↔	↑	↔	↑
Power Supplies (DC/DC)	Murata PS	10-18	↔	↑	↔	↑
	Recom	15-17	↔	↑	↔	↑
	Wall Industries	8-10	↔	↔	↔	↔
	CUI Inc.	11-28	↔	↑	↔	↑
PCB Connector	TE Connectivity	12-16	↔	↑	↔	↑
	Amphenol	8-10	↔	↑	↔	↑
	Adam Tech	16-18	↔	↑	↔	↑
	JST	12-16	↔	↔	↔	↔

Factory Lines					Open Market	
Product	Brand	Lead time weeks	Prognosis	Pricing Trend	Availability	Pricing Trend
Lightning Connectors	Kyocera	10-12	↔	↑	↔	↑
	TE Connectivity	12-16	↔	↑	↔	↑
	WAGO	12-14	↔	↔	↔	↔
Terminal Blocks & Crimps	TE Connectivity	12-16	↔	↑	↔	↑
	METZ Connect	10-16	↔	↑	↔	↑
	Wieland Electric	12-16	↔	↑	↔	↑
	Major League Electronics	6-8	↔	↔	↔	↔

Electromechanical suppliers continued expanding high-reliability connectivity and switching solutions in Q2 2026. TE Connectivity introduced KISSLING high-power relays, while Samtec released 26.5 GHz SMA edge-mount connectors for 5G, aerospace, and test applications. Amphenol and Molex continued expanding rugged interconnect portfolios.

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End of Life (EOL)

Microchip

Product	EOL	Notes
UF6000-VE	Oct 2026	No direct drop-in; consult Microchip's latest PCN documentation for recommended design-in alternatives.
UF7000-VE	Oct 2026	Discontinued; review the technical cross-reference list provided in the official PCN for migration paths.

Renesas

Product	EOL	Notes
MCU PLC26005	Jul 2026	Transition to active Renesas RA or RX devices as recommended by Renesas.
ICs PLC26005	Jul 2026	Pin-compatible replacements identified through Renesas lifecycle portal.

Infineon

Product	EOL	Notes
PD_355_25	Nov 2026	Last delivery date is Nov 30, 2026. Transition to newer OptiMOS™ generations for improved efficiency.
Obsolete IGBT Modules	Nov 2026	EOL status; consider migrating to the latest TRENCHSTOP™ series for similar power density and thermal performance.

NXP

Product	EOL	Notes
DSP56F801F A60E	Jul 2026	Migrate to MCX, Kinetis, or i.MX RT families depending on application.
DSP56F803B U80E	Jul 2026	Replacement guidance recommends MC56F8xxx DSP family where applicable.

Diodes Incorporated

Product	EOL	Notes
MUR160-A52	Jul 2026	Manufacturer provides recommended active rectifier substitute in PCN 2757.
UF3004-A	Jul 2026	Replace with current ultrafast rectifier listed in Diodes PCN.

End of Life (EOL)

Analog Devices

Product	EOL	Notes
REF01R000C	Jul 2026	Replace with REF01-000C
REF02R000C	Jul 2026	Replace with REF02-000C

Central Semiconductor

Product	EOL	Notes
MPQ2222	Nov 2026	Use the replacement transistor listed in PDN01291.
SOD-323	Jul 2026	Transition to SOD-323F package replacements.

BCM Advanced Research

Product	EOL	Notes
ESM-CFH COM	Jul 2026	Migrate to newer COM Express platforms recommended by BCM.
EMX-C246P	Jul 2026	BCM recommends migration to current Intel-based motherboard platforms.

Perle Systems

Product	EOL	Notes
IOLAN SDG4 LE	Dec 2027	Product discontinued; no direct replacement published.
IOLAN SDS4 P	Aug 2027	Replace with IOLAN SDG4 P Device Server.

Analog Devices

Product	EOL	Notes
REF01R000C	Aug 2026	Replace with REF01-000C (pin-compatible).
REF02R000C	Aug 2026	Replace with REF02-000C (pin-compatible).

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AI Cameras

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- **Dual Mode Flexibility:** Full support for both SD and SPI modes, supporting legacy and modern systems.
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- **Mechanical Ruggedness:** * Rated for 10,000 insertion/removal cycles.
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Diodes Inc. Shortage

The ongoing shortage affecting Diodes Incorporated components is creating new procurement challenges for OEMs, EMS providers, and industrial manufacturers. Extended lead times, product allocation, and increasing costs are making it more difficult to secure critical discrete semiconductors and timing devices, prompting many organizations to evaluate qualified alternative sources.

1. What's Driving the Shortage?

Lead times that previously averaged eight to ten weeks have expanded to more than 48 weeks across several Diodes Incorporated product families.

The primary driver is the rapid expansion of AI infrastructure. AI servers require large volumes of MOSFETs, timing ICs, and high-efficiency power devices for power management, signal conditioning, and switching applications. At the same time, shortages affecting other discrete semiconductor manufacturers have redirected demand toward Diodes Incorporated, placing additional pressure on manufacturing capacity and product availability.

2. Product Families Under Pressure

The greatest constraints are affecting components widely used in power conversion, industrial automation, and embedded systems. High-demand categories include:

Product Family	Typical Application	Why It's in High Demand
MOSFETs (N/P Channel)	DC-DC conversion, load switching	Core to server and industrial power stages
SiC Schottky Diodes	High-efficiency rectification	Preferred for high-power, low-loss designs
Timing & Logic ICs (74LVC, buffers, translators)	Signal timing, logic conditioning	Ubiquitous on AI and embedded motherboards
Zener & Schottky Diodes	Voltage regulation, fast switching	Present in nearly every power and control circuit
Bipolar Transistors	Biasing, amplification	Foundational analog building block

3. Evaluating Alternative Solutions

To minimize disruption, many engineering teams are qualifying replacement components with comparable electrical performance and package compatibility. Matching key specifications, such as voltage ratings, current capacity, on-resistance, and standard package footprints, can help reduce redesign efforts and accelerate component qualification.

Diotec Semiconductor offers a broad portfolio of Schottky diodes, Zener diodes, rectifiers, TVS protection devices, and small-signal discretes that align with many Diodes Incorporated product families. These alternatives can provide greater sourcing flexibility while helping maintain electrical performance and PCB compatibility.

4. How ASC Global Can Help

ASC Global supports customers through a combination of global sourcing capabilities and authorized distribution. When available, our worldwide supply network helps secure Diodes Incorporated components for ongoing production requirements.

As an authorized distributor for Diotec Semiconductor, ASC Global also provides specification-aligned alternatives with full traceability and factory support, enabling customers to reduce lead-time risk, accelerate qualification, and maintain production continuity.

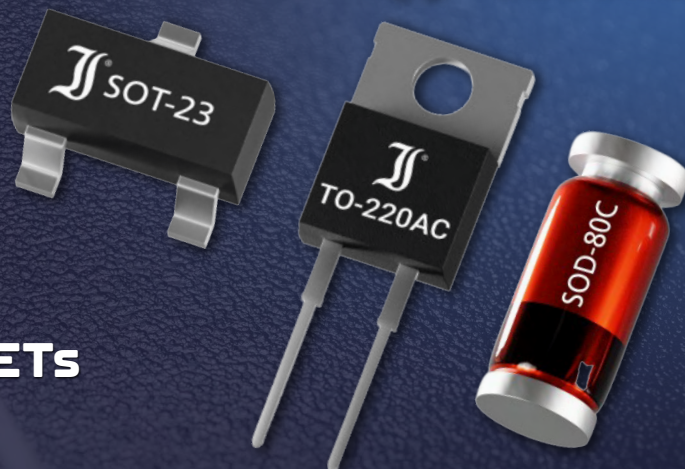
As semiconductor supply conditions continue to evolve throughout 2026, proactive sourcing strategies and qualified alternate components remain essential for reducing supply chain risk and supporting uninterrupted manufacturing.

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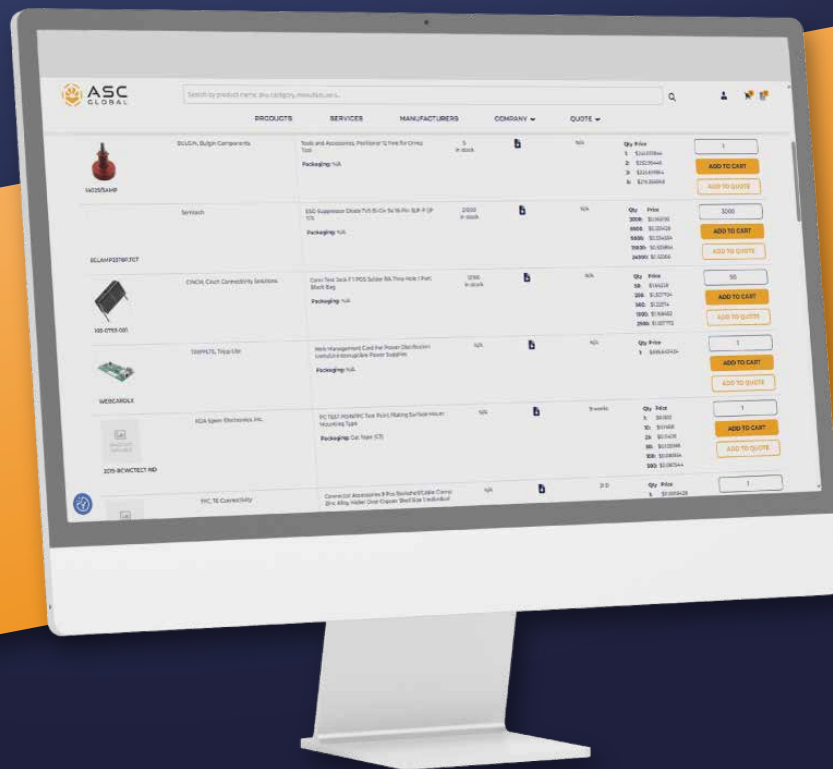
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Section 232 Semiconductor Tariffs

1. Executive Summary

Six months after the implementation of the U.S. Section 232, their effects continue to shape procurement decisions throughout the global electronics industry. Rather than being a short-term pricing event, the tariffs have accelerated broader changes in sourcing strategies, inventory planning, and supply chain risk management.

According to a June 2026 analysis by the Information Technology and Innovation Foundation (ITIF), the long-term economic impact extends well beyond the semiconductor products directly affected by the tariffs. Higher component costs, shifting manufacturing strategies, and ongoing geopolitical uncertainty continue to influence the availability and pricing of electronic components across multiple industries.

2. Market Overview

The semiconductor market remains under pressure as growing demand for AI, industrial automation, automotive electronics, and advanced computing coincides with an increasingly complex trade environment. To reduce tariff exposure and geopolitical risk, manufacturers are diversifying suppliers, expanding regional production, and strengthening inventory strategies.

While improving long-term resilience, these measures have contributed to pricing volatility and periodic supply imbalances. According to ITIF, prolonged tariffs could increase production costs and reduce competitiveness, making supplier flexibility and sourcing reliability critical priorities for procurement organizations.

3. Market Impact

What procurement teams should expect during Q3 2026

- Continued pricing volatility across selected semiconductor categories.
- Longer planning cycles as manufacturers diversify production and sourcing locations.
- Increased emphasis on supplier qualification and alternative component strategies.
- Greater focus on inventory optimization to reduce exposure to future trade disruptions.
- Procurement decisions increasingly driven by geopolitical risk rather than price alone.

4. Procurement Outlook

The semiconductor industry has entered a period where geopolitical developments and trade policy are becoming permanent procurement variables rather than temporary market events. Organizations relying on single-source suppliers or just-in-time purchasing strategies remain more vulnerable to pricing fluctuations and unexpected supply disruptions.

As manufacturers continue investing in AI, data centers, industrial automation, and next-generation electronics, resilient supply chains will become a key competitive advantage. Companies that proactively diversify suppliers, validate component alternatives, and strengthen inventory planning will be better positioned to maintain production continuity despite ongoing market uncertainty.

5. ASC Global Recommendation

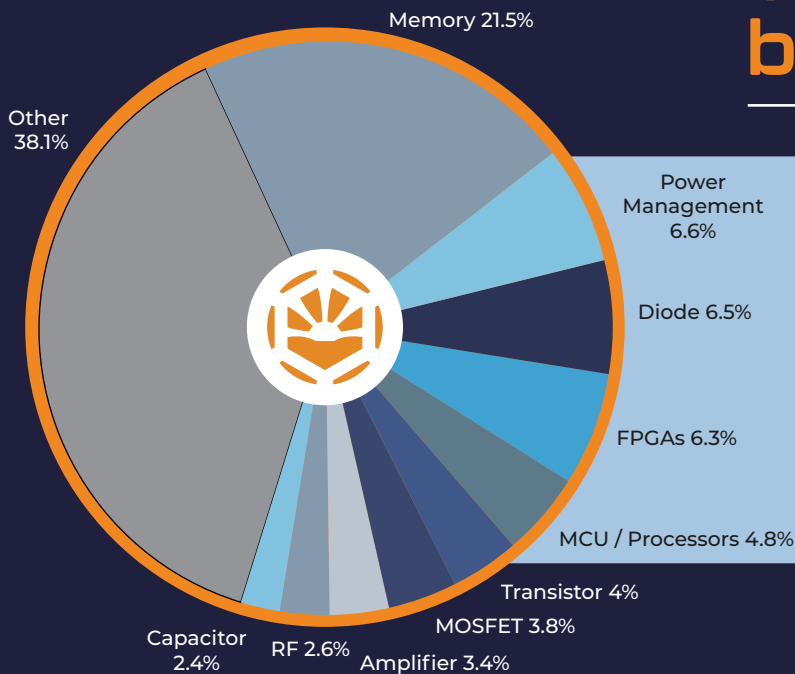
The combined impact of the January 2026 Section 232 tariffs, ongoing geopolitical uncertainty, and manufacturer-specific shortages such as Nexperia reinforces the need for proactive supply chain management. ASC Global helps manufacturers reduce procurement risk through global sourcing, qualified alternative components, product validation, strategic inventory programs, and access to a worldwide network of vetted suppliers. These solutions enable customers to improve component availability, control procurement costs, and maintain uninterrupted production despite evolving market conditions.

6. ASC Global Recommendation

- Six months after implementation, the January 2026 Section 232 tariffs continue to reshape global semiconductor procurement.
- Industrial manufacturers, automotive suppliers, aerospace companies, medical device producers, and telecommunications providers remain among the sectors most affected.
- The ongoing Nexperia shortage continues to create sourcing challenges for discrete semiconductor devices, reinforcing the importance of qualified alternatives.
- Procurement organizations should expect continued pricing volatility, selective lead-time extensions, and increased emphasis on supplier diversification through the remainder of 2026.
- Building a resilient, diversified supply chain remains one of the most effective strategies for minimizing risk and maintaining production continuity.

Test & Failure Rates

Test Rates by Device Type



Memory devices led testing at 21.5%, reflecting AI-driven demand and constrained supply. Elevated activity in power management ICs, diodes, and FPGAs highlights continued mature-node shortages, reinforcing the need for rigorous authentication and quality verification when sourcing components through alternative supply channels.

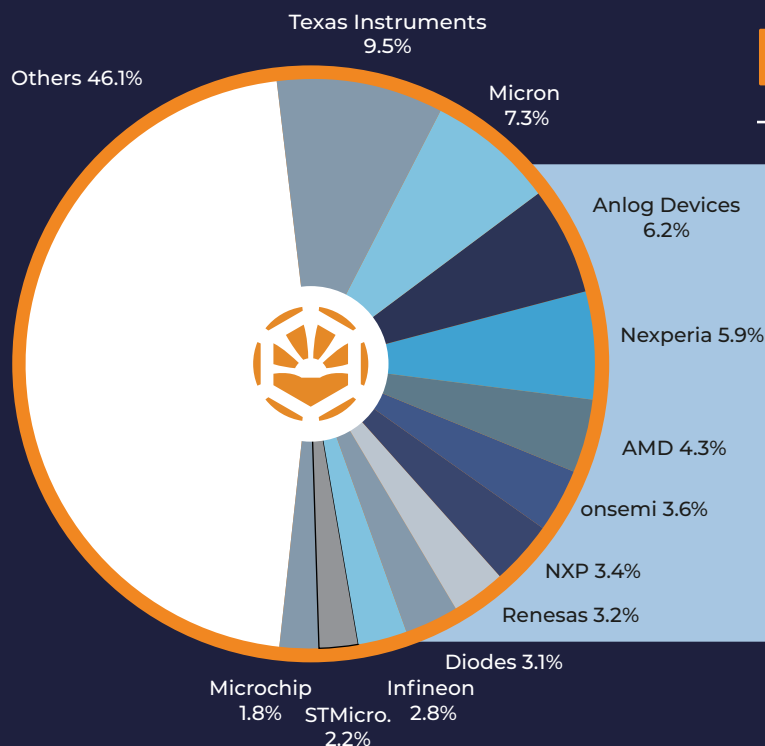
Top 10 Component Types by Failure Rate

Here's a list of the top 10 device types most likely to fail our quality tests in June.

1. Hard Drives
2. Filter
3. CPU
4. Isolated DC / DC Converters
5. Transceiver
6. System on Chip (SOC)
7. Optocoupler
8. Microprocessor
9. FPGA
10. RF and Wireless

This ranking is determined by the proportion of failed results compared to the total units tested in each category. While some failures stem from aging or mishandling, others could indicate more serious quality issues or potential counterfeit threats.

Test Rates by Manufacturer



Texas Instruments led submitted components at 9.5%, followed by Micron Technology and Analog Devices. This distribution reflects procurement demand, not product quality, as AI, industrial automation, and high-performance computing drive increased sourcing, prompting organizations to rely on independent component authentication and verification before production deployment.

Top 10 Manufacturers by Failure Probability

Regarding manufacturer origin, these ten brands recorded the highest test failure rates in December.

- | | |
|-------------------------------|----------------------|
| 1. MACOM Technology Solutions | 6. REALTEK |
| 2. Seagate | 7. Vicor Corporation |
| 3. Hynix | 8. Pulse Electronics |
| 4. Navitas | 9. Intel |
| 5. Cypress | 10. ADI |

This does not indicate widespread issues but suggests areas that may benefit from further supplier verification or risk mitigation measures.



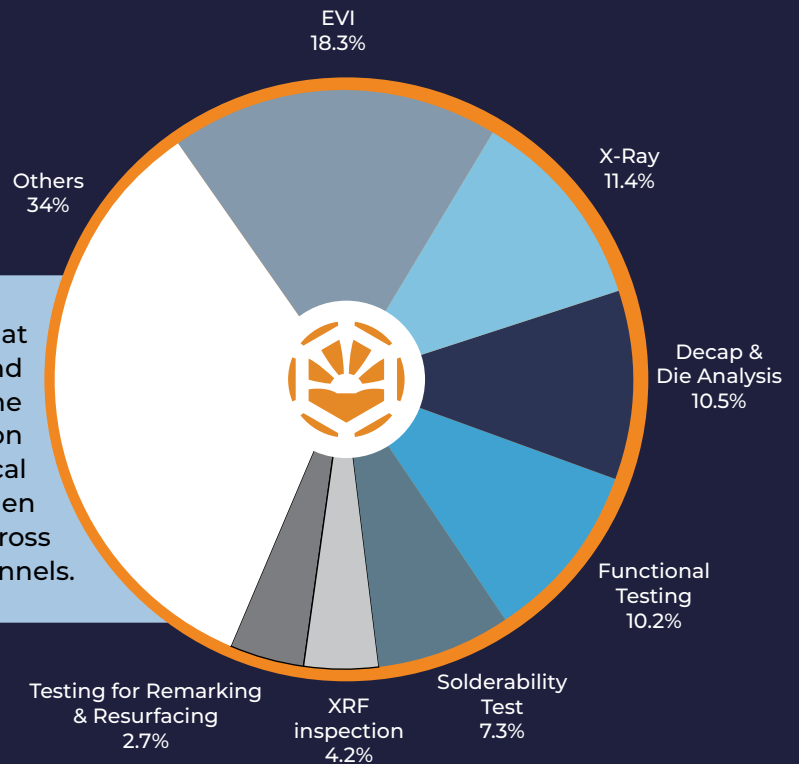
Driving Electronic Sustainability

- Energy-efficient operations
- Sustainable shipping practices
- Supply chain transparency
- Green sourcing

Test Types & Results

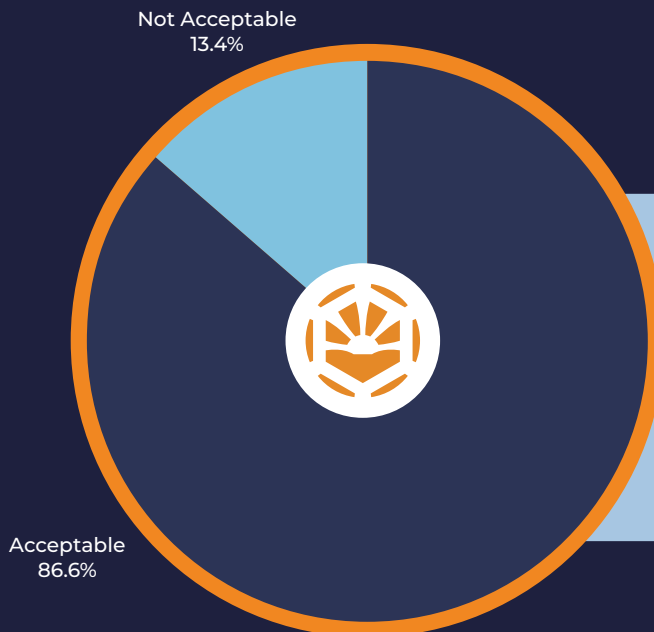
Test Types

External Visual Inspection led May testing at 18.3%, while X-ray, decapsulation, and functional testing remained highly utilized. The results reflect growing reliance on comprehensive physical and electrical verification as organizations strengthen counterfeit detection and authentication across increasingly diverse component sourcing channels.



Test Results

May testing found 86.6% of components acceptable and 13.4% not acceptable. The elevated rejection rate reflects ongoing supply chain pressures as AI-driven demand tightens availability and increases sourcing risk. Comprehensive inspections, including EVI, X-ray, decapsulation, and functional testing, remain essential for detecting counterfeit, refurbished, and defective components before production.



Hot Commodities

Compiled from diverse sources, this data provides guidance. Treat it accordingly. ASC Global offers premier supply chain programs to mitigate market volatility. Contact your Account Manager for details.

 Analog

 Power Products

 Passives

 Memory

 Logic & Digital

 Electromechanical

ASC's Picks

Type	Product #	Manufacturer	Lead Time weeks	Pricing Trend	Prognosis
	ICM42688P	TDK	45	↔	↔
	MT41K256M16TW107ITP	Micron	37-53	↔	↔
	REF200AU	Texas Instruments	8-16	↔	↔
	MT41K256M16TW107P	Micron	40-53	↔	↔
	ISL99390FRZTR5935	Renesas	24-36	↔	↔
	REF200AU2K5	Texas Instruments	24-32	↔	↔
	MT41K128M16JT125ITK	Micron	20-30	↔	↔
	MT40A512M16TB062ER	Micron	50-60	↔	↔
	MT40A512M16LY062EITE	Micron	8-16	↔	↔
	ICM-20948	TDK	50-64	↔	↔
	STM32F405RGT6	STM	20-30	↔	↔
	SDSDQAF3008GI	SandDisk	50-64	↔	↔

Product Updates

Integrated Circuits

AI infrastructure continues driving strong IC demand as **NVIDIA**, **AMD**, **Broadcom**, and **Marvell** expand accelerator deployments, tightening advanced-node capacity while increasing procurement lead times for high-performance computing applications.

Automotive, industrial, and networking IC demand remains stable, but manufacturers continue prioritizing AI-related production, limiting supply flexibility for legacy devices and mature-node components from **Infineon**, **Texas Instruments**, and **STMicroelectronics**.

FPGA

FPGA demand is accelerating as **AMD Xilinx** and **Intel** support AI networking, edge computing, and high-speed connectivity, with hyperscale infrastructure investments sustaining healthy order activity through Q3 2026.

Communications and industrial automation customers increasingly deploy FPGA solutions for adaptable computing, although allocation priorities toward AI infrastructure may extend delivery schedules for selected high-performance programmable devices.

Passives

Murata, **TDK**, **Yageo**, and **Kyocera AVX** report steady passive component consumption supported by automotive electronics, industrial automation, and AI server expansion, maintaining balanced inventories across most standard product categories.

High-capacitance MLCCs and power inductors designed for AI servers remain strongest-performing segments, while commodity passive components experience stable pricing with improved availability compared with previous supply cycles.

eMMC

eMMC demand remains concentrated in embedded, industrial, networking, and entry-level consumer applications as **Samsung**, **Kioxia**, **Western Digital**, and **Micron** increasingly emphasize higher-value enterprise memory production.

AI-driven wafer allocation continues reducing manufacturing flexibility for legacy embedded memory products, encouraging OEMs to secure longer-term purchasing agreements for critical eMMC supply requirements.

RDIMM

DDR5 RDIMM pricing continues rising as **Micron**, **Samsung**, and **SK hynix** prioritize AI server deployments, while hyperscale customers aggressively reserve production capacity for next-generation data centers.

Enterprise buyers face longer procurement lead times as cloud providers increase purchases of high-capacity **DDR5 RDIMMs** supporting inference workloads and expanding AI infrastructure investments worldwide.

Product Updates

SSD

Enterprise SSD demand continues strengthening as **Micron**, **Samsung**, **Solidigm**, and **Kioxia** expand PCIe Gen5 and Gen6 portfolios optimized for AI inference, training, and hyperscale storage platforms.

Capacity prioritization toward enterprise SSD production tightens NAND availability for other applications, supporting continued price increases and strategic allocation across data-center focused storage products.

HDD

HDD demand increasingly centers on high-capacity enterprise storage, with **Seagate** and **Western Digital** benefiting from expanding AI data lakes requiring economical large-scale archival storage alongside flash solutions.

Although enterprise SSD adoption continues accelerating, HDD technology remains essential for hyperscale storage infrastructure where cost-per-terabyte and long-term scalability remain primary procurement considerations.

Server CPU

Server CPU demand remains robust as AMD EPYC and Intel Xeon processors support AI inference clusters, with lead times extending because of strong hyperscale infrastructure expansion.

Cloud providers continue pairing higher-core-count server CPUs with advanced AI accelerators, increasing procurement activity while maintaining elevated pricing across enterprise computing platforms during Q3 2026.

GPU

AI accelerator demand remains exceptionally strong as **NVIDIA** Blackwell and **AMD Instinct** platforms dominate hyperscale investments, sustaining constrained availability despite expanding manufacturing and packaging capacity.

GPU procurement increasingly focuses on inference deployments, driving continued investments in memory bandwidth, networking, and power-efficient server architectures across global cloud infrastructure providers.

Motherboards

Enterprise motherboard development increasingly targets AI-ready platforms supporting latest **Intel Xeon** and **AMD EPYC** processors, with **MSI**, **ASUS**, **Supermicro**, and **Gigabyte** expanding high-density server offerings.

Demand for advanced server motherboards continues increasing as OEMs integrate higher memory capacity, faster PCIe connectivity, and enhanced power delivery for AI-focused computing infrastructure deployments.

Manufacturer Updates

SK Hynix

SK hynix continues expanding HBM production capacity to meet accelerating AI demand, strengthening partnerships across the AI ecosystem while maintaining premium pricing as memory supply remains constrained through 2026.

Samsung

Samsung is increasing investment in advanced HBM and AI memory technologies while optimizing production capacity, positioning itself to capture growing hyperscale demand despite persistent supply constraints across premium memory markets.

NXP

NXP continues focusing on automotive, industrial, and edge computing applications, where software-defined vehicles and intelligent connectivity sustain long-term semiconductor demand despite mixed consumer electronics conditions.

Intel

Intel remains focused on expanding its AI-enabled Xeon processor portfolio while strengthening foundry and advanced packaging capabilities to compete more effectively in enterprise computing and hyperscale infrastructure markets.

Nvidia

NVIDIA continues dominating AI accelerator deployments as hyperscale cloud providers expand infrastructure investments, driving sustained demand throughout its semiconductor supply chain, including advanced memory, networking, and packaging partners.

STMicroelectronics

STMicro. maintains stable industrial and automotive demand while benefiting from Europe's semiconductor investment initiatives, although AI-related capacity prioritization continues influencing broader production planning and component allocation.

Microchip Technology

Microchip Technology continues experiencing stable industrial and embedded demand, emphasizing inventory normalization and long-term customer support while AI infrastructure investment gradually improves broader semiconductor market confidence.

Infineon

Infineon benefits from resilient automotive electrification and industrial automation demand while participating in Europe's semiconductor recovery, supported by continued investments in power management and energy-efficient technologies.

Micron

Micron reported exceptionally strong AI-driven demand, securing multi-year customer commitments totaling billions of dollars as HBM and enterprise memory shortages continue supporting higher pricing and long-term revenue visibility.

Texas Instruments

Texas Instruments maintains disciplined manufacturing expansion and analog leadership while industrial demand gradually stabilizes, supported by long product lifecycles and resilient automotive electronics production worldwide.

Manufacturer Updates

AMD

AMD continues expanding EPYC processors and Instinct AI accelerators, strengthening its position in hyperscale computing as enterprise customers increase investments in AI training and inference infrastructure.

Lattice

Lattice benefits from increasing demand for low-power programmable logic supporting industrial automation, embedded AI, and edge computing applications where energy efficiency remains a critical purchasing consideration.

Skyworks

Skyworks maintains steady wireless connectivity demand while expanding solutions supporting Wi-Fi, IoT, automotive, and next-generation communications, offsetting slower smartphone market recovery with diversified end-market exposure.

Onsemi

onsemi continues benefiting from automotive electrification, intelligent power management, and industrial automation investments, reinforcing demand for silicon carbide and energy-efficient semiconductor technologies.

Vishay

Vishay maintains healthy demand across passive components and discrete semiconductors, supported by automotive, industrial, and power management applications while inventories continue normalizing throughout the electronics supply chain.

TSMC

TSMC continues operating at high advanced-node utilization as AI accelerator demand drives sustained customer investment, reinforcing leadership in leading-edge manufacturing and advanced semiconductor packaging technologies.

Amphenol

Amphenol continues benefiting from accelerating AI server deployments, as demand for high-speed interconnects, power solutions, and data-center connectivity products remains strong throughout global infrastructure expansion.

Qualcomm

Qualcomm is accelerating its expansion into AI-enabled data center processors while maintaining leadership in mobile connectivity, broadening revenue opportunities beyond smartphones through enterprise computing initiatives.

Renesas

Renesas continues strengthening automotive and embedded processing portfolios as industrial automation, connected vehicles, and intelligent edge applications support stable semiconductor demand through mid-2026.

GlobalFoundries

GlobalFoundries continues expanding specialty manufacturing capabilities for automotive, communications, and defense markets while emphasizing differentiated process technologies supporting resilient demand outside leading-edge AI semiconductor production.

Earnings Recap

Automotive

Toyota Motor Corp.

- Revenue: \$160.4 B (+4.4% YoY)
- Net income: \$12.2 B
- Net Profit Margin: 7.6%

General Motors

- Revenue: \$44.0 B (-1.0% YoY)
- Net income: \$2.6 B
- Net Profit Margin: 6.0%

Ford Motor Company

- Revenue: \$50.2 B (+5.0% YoY)
- Net income: \$1.8 B
- Net Profit Margin: 3.6%

Automotive manufacturers maintained resilient financial performance during Q2 2026 despite persistent tariff pressures, elevated material costs, and supply-chain uncertainty. Demand for hybrids, software-defined vehicles, and AI-enabled technologies continued supporting revenue growth, while profitability remained dependent on operational efficiency, regional sales mix, and disciplined cost management.

AI and Data Center

Microsoft Corp.

- Revenue: \$81.3 B (+17% YoY)
- Net Income: \$38.5 B
- Net Profit Margin: 47.4%

NVIDIA Corp.

- Revenue: \$46.7 B (+56% YoY)
- Net Income: \$26.4 B
- Net Profit Margin: 56.6%

Alphabet Inc.

- Revenue: \$109.9 B (+22% YoY)
- Net Income: \$62.6 B
- Net Profit Margin: 56.9%

AI infrastructure spending remained exceptionally strong throughout Q2 2026, with hyperscalers accelerating investments in GPUs, custom AI silicon, networking, and data centers. Enterprise AI adoption continued driving cloud expansion, while demand for advanced memory, power, and cooling solutions sustained robust supply-chain activity despite ongoing capacity and infrastructure constraints.

Earnings Recap

Automation Industry

Siemens AG

- Revenue: \$23.1 B (+6% YoY)
- Net Income: \$2.1 B
- Net Profit Margin: 13.3%

ABB Ltd

- Revenue: \$8.3 B (+5% YoY)
- Net Income: \$1.1 B
- Net Profit Margin: 13.3%

Rockwell Automation

- Revenue: \$2.0 B (+4% YoY)
- Net Income: \$0.28 B
- Net Profit Margin: 14%

The automation sector in Q2 2026 showed steady growth driven by industrial digitalization, AI-enabled manufacturing, and energy efficiency investments. Siemens, ABB, and Rockwell benefited from strong demand in process automation, robotics, and smart factory solutions. However, margin pressure persisted due to supply chain costs and uneven regional industrial recovery.

Consumer and Personal Computing

Apple Inc.

- Revenue: \$101.4 B (+7% YoY)
- Net Income: \$26.8 B
- Net Profit Margin: 26.4%

HP Inc.

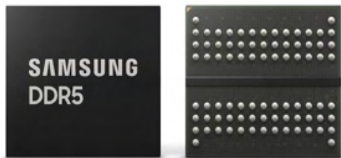
- Revenue: \$13.8 B (+5% YoY)
- Net Income: \$0.72 B
- Net Profit Margin: 5.2%

Lenovo Group

- Revenue: \$15.9 B (+3% YoY)
- Net Income: \$0.34 B
- Net Profit Margin: 2.1%

Consumer and personal computing markets in Q2 2026 showed moderate recovery, driven by AI-enabled PCs, premium device demand, and enterprise refresh cycles. Apple led growth through ecosystem integration, while Lenovo and HP saw gradual PC stabilization. Margins remained under pressure due to component costs and competitive pricing across global markets.

Industry Updates

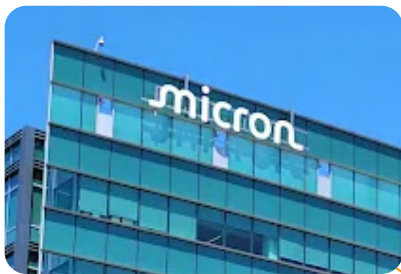


Samsung Targets Higher DRAM Pricing

Samsung is seeking up to a 20% DRAM price increase for Q3 2026 as AI-driven demand and tight memory supply continue to strengthen the market. LPDDR prices may rise even further, potentially increasing costs for PCs, smartphones, and AI-enabled devices.

TSMC Accelerates Arizona Fab Expansion

TSMC is doubling its Arizona manufacturing expansion to increase U.S. semiconductor production, supporting rising demand for advanced chips. The investment strengthens domestic supply chain resilience, expands leading-edge manufacturing capacity, and aligns with U.S. efforts to reduce dependence on overseas semiconductor production.



Micron Expands U.S. Investment

Micron increased its planned U.S. investment to more than \$250 billion through 2035, expanding domestic memory manufacturing and strengthening wafer supply. The initiative supports surging AI-driven demand, improves long-term supply chain resilience, and is expected to create more than 90,000 jobs.

China Restricts Helium Exports

China has temporarily restricted helium exports to protect domestic supply amid ongoing global shortages. Because helium is essential for EUV lithography and advanced chip manufacturing, the measure may increase procurement risks, pricing volatility, and supply chain uncertainty for semiconductor manufacturers worldwide.



Industry Updates



Bosch Launches U.S. Production

Bosch has begun sample production at its first U.S. semiconductor plant in California, manufacturing silicon carbide chips for electric vehicles, AI infrastructure, and energy systems. Backed by \$225 million in CHIPS Act funding, the facility strengthens domestic semiconductor manufacturing and supply chain resilience.

Nexchip Secures Major Funding

Chinese foundry Nexchip raised \$880 million through its Hong Kong listing to expand 12-inch wafer production and advanced process technologies. The investment strengthens domestic semiconductor manufacturing capacity, supporting automotive, industrial, and consumer electronics while reducing dependence on overseas fabrication.



TSMC Packaging Expansion

TSMC continues aggressively expanding CoWoS advanced packaging capacity to reduce AI accelerator bottlenecks. Hyperscale demand from NVIDIA and AMD drives sustained utilization, while OSAT partners increase output to support growing GPU and AI compute deployment requirements across global data center markets.

SK Hynix Revises Memory Contracts

SK Hynix has reportedly removed price caps from long-term memory supply agreements, allowing prices to better reflect market conditions. The move highlights confidence in sustained AI-driven demand and signals tighter memory supply dynamics compared with competitors maintaining pricing restrictions.



MANUFACTURING CAPABILITIES



Benefits

- **Cost Savings:** Enjoy competitive prices on all your supply chain needs and additional rebates on bulk purchases.
- **Reduced risk:** Improve your supply chain resilience by increasing the sources for your vital components.
- **Better service:** Better technical support, faster turnaround times, or more flexible ordering options.

Products

Passive

- | | |
|--------------------|------------------|
| • LED Components | • EMI Filters |
| • Fuses | • Photo Controls |
| • Circuit Breakers | • Relays |
| • Switches | • Resistor |
| • Capacitors | • Thermistor |

Semiconductors

- | | |
|----------------------------------|---------------------|
| • Coin Batteries | • Sensor components |
| • Cylindrical Batteries | • Diodes |
| (Acoustic and Haptic technology) | • Regulator |

Drop-In Replacements

Kingbright | Cree LED | AMS | OSRAM |
 Lite-On | Broadcom Limited | Lumileds
 | Ledil | Luminus Devices | Mersen |
 Littelfuse | Eaton/Bussmann

Industry Applications

- | | |
|------------------------|-----------------------|
| • Automotive | • Lighting |
| • Industrial | • New Energy |
| • Medical Devices | • Telecommunication |
| • Consumer Electronics | • Home Appliances |
| • Aviation | • Security Protection |
| • Marine | • Power Trip |
| • Power Supply | • Networking |

MARKET REPORT

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Aerospace &
Defense



Automotive



Aviation



Communications



Consumer
Electronics



Energy



Industrial



Medical

Our mission statement is to create an easy and accessible component distribution experience for all our clients.

LOCATIONS

Global presence while providing unparalleled customer service. 9 offices strategically placed in major regions of the global electronic economy.

United States Headquarters

7880 N University Dr. Ste. 100
Tamarac, FL 33321

EUROPE

United Kingdom
Poland
Germany
Italy
Hungary

CHINA

Shenzhen
Hong Kong

SINGAPORE*

MEXICO

Guadalajara, Jalisco

INDIA*

*Offices coming soon



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